ASSOCIATION CON-	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				ials and Mfg Information				
upplier In	formation													
Company name*			Company unique ID			U	Unique ID Authority				Response Date*			
nsemi											2025-06-03			
Contact Name	:	Title - Contact			P	Phone - Contact*				Email - Contact*				
Product-Env-S	Stewards		Product Enviro Compliance			ı	NA				Product-Env-Stewards@onsemi.com			
uthorized Re	epresentative*	Title - Representative			P	Phone - Representative*			Email - Representative*					
Product-Env-S	Stewards	Product Enviro Compliance			r	NA				Product-Env-Stewards@onsemi.com				
Red	quester Item Number			Mfr Item Name			Effective Date	Version	N	Manufacturing Site	W	eight*	UOM	Unit Type
				PT8 N 30/20 erclip	56 Si		2025-06-03		P	PBB		22.136	mg	Each
	ring Process Informa			A.11				D 1 T		M. William D. I		N. 1	CD CL	,
ž ž		•		STD-020 MSL I	Rating	Peak Process Body Tempe		Τ'				er of Reflow Cyc	les	
•	tte Tin (Sn) - annealed		CU Alloy	1			260		C	30	second	s 3		
omments														
	num time at peak tempera	8												
or more infor	rmation regarding materia	l composition	please refer to	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Islability and the Company's remedies for issues that arise regarding information the Supplier pro											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	19.1	mg	Supplier	Zinc (Zn)	7440-66-6		0.0229	mg
			Supplier	Iron (Fe)	7439-89-6		0.4489	mg
			Supplier	Copper (Cu)	7440-50-8		18.6225	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0057	mg
Die	2.54	mg	Supplier	Silicon (Si)	7440-21-3		2.54	mg
Lead Frame	46.436	mg	Supplier	Silver (Ag)	7440-22-4		0.065	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0464	mg
			Supplier	Iron (Fe)	7439-89-6		0.9752	mg
			Supplier	Copper (Cu)	7440-50-8		45.303	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0464	mg
Mold Compound-Black	42.7	mg		Epoxy resin	proprietary data		5.6791	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0854	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		36.9355	mg
Plating	8.33	mg	Supplier	Tin (Sn)	7440-31-5		8.33	mg
Solder Paste	3.017	mg	Supplier	Silver (Ag)	7440-22-4		0.0754	mg
			A	Lead (Pb)	7439-92-1	7a	2.7907	mg
			Supplier	Tin (Sn)	7440-31-5		0.1508	mg
Wire Bond - Cu	0.013	mg	Supplier	Palladium (Pd)	7440-05-3		0.0002	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0128	mg